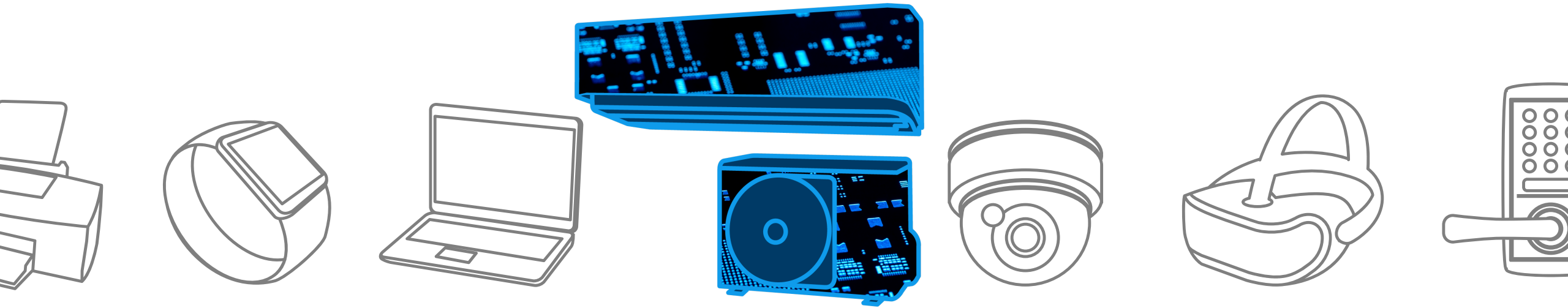
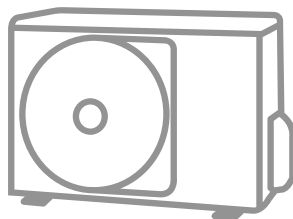
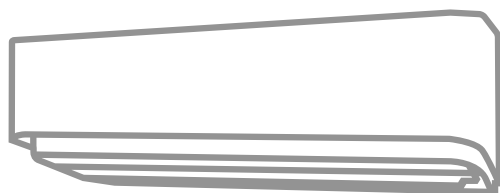
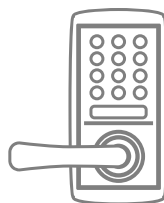


Air Conditioner

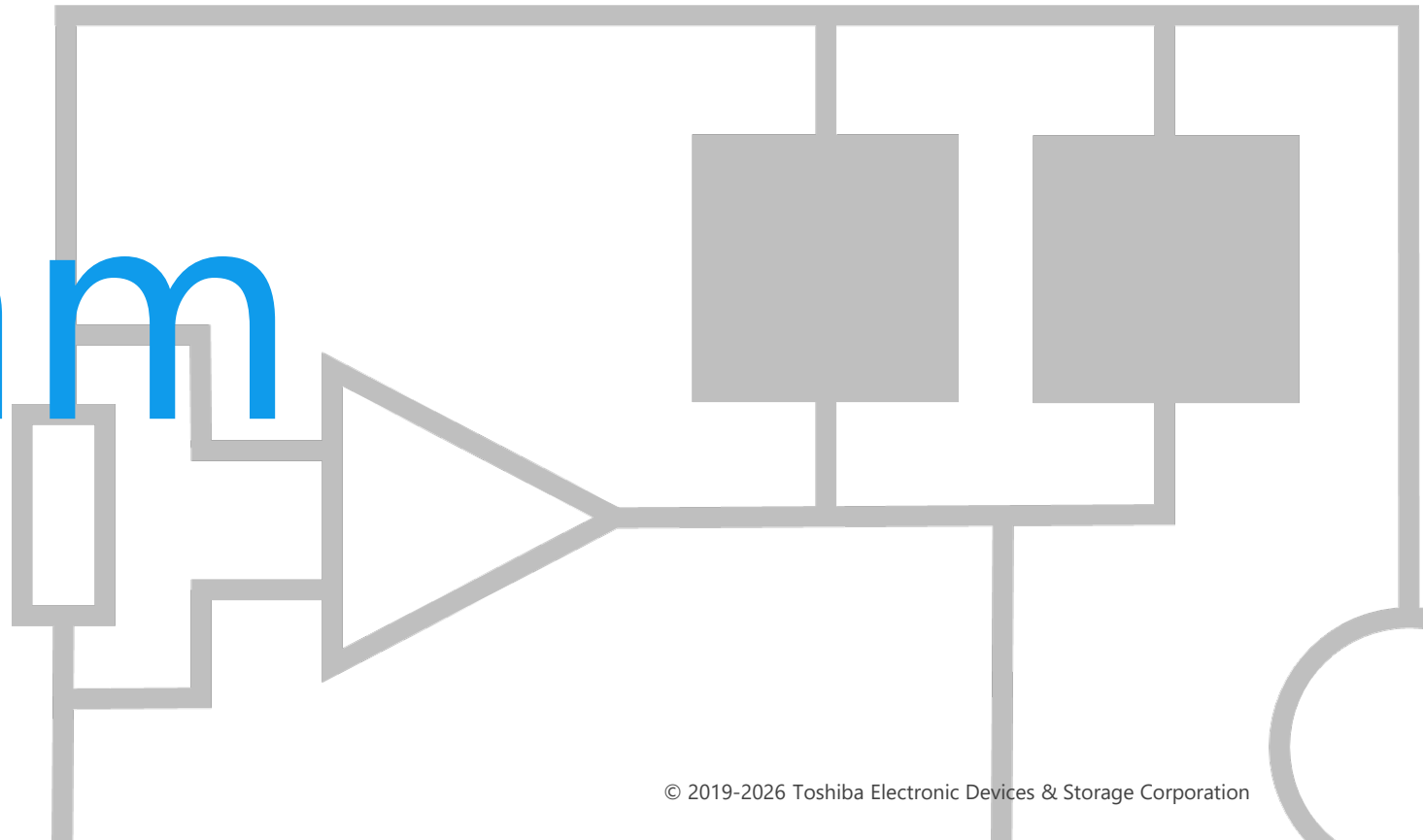
Solution Proposal by Toshiba



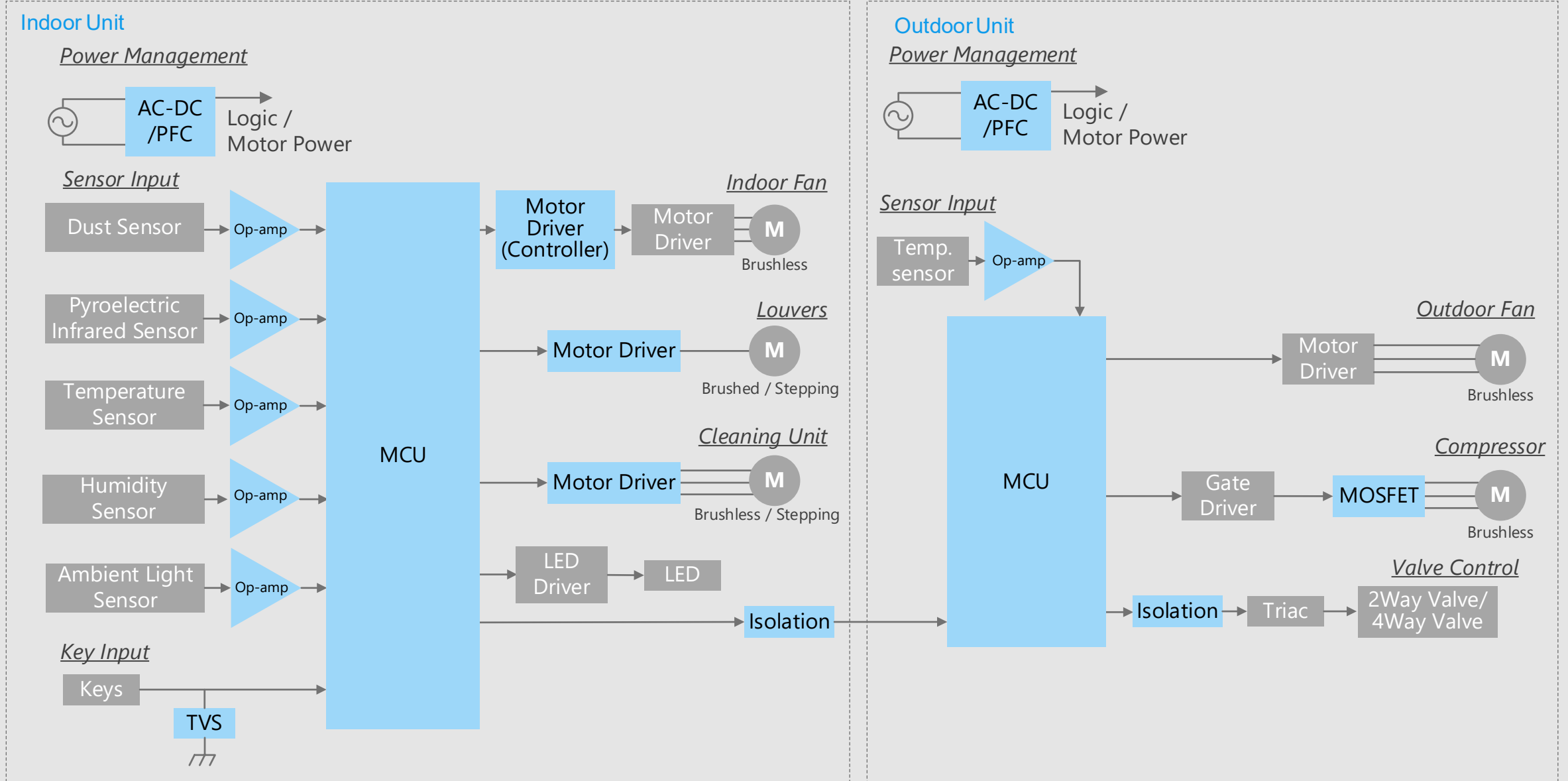


Toshiba Electronic Devices & Storage Corporation provides comprehensive device solutions to customers developing new products by applying its thorough understanding of the systems acquired through the analysis of basic product designs.

Block Diagram



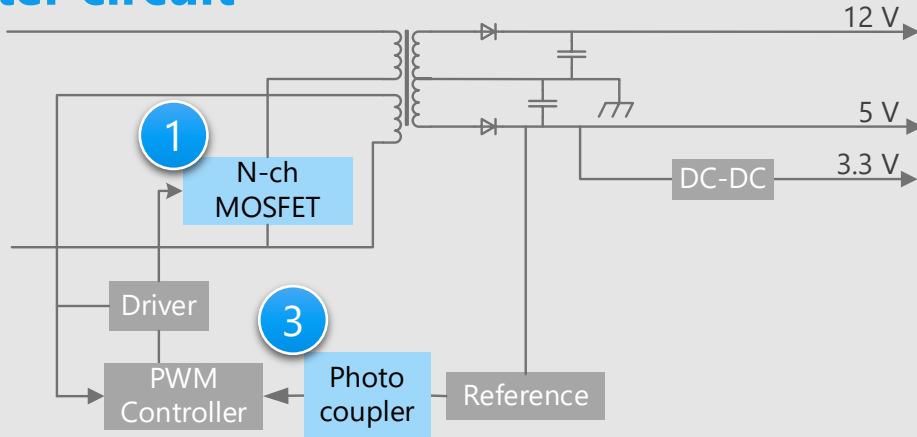
Air Conditioner Overall Block Diagram



Air Conditioner Details of AC-DC converter unit

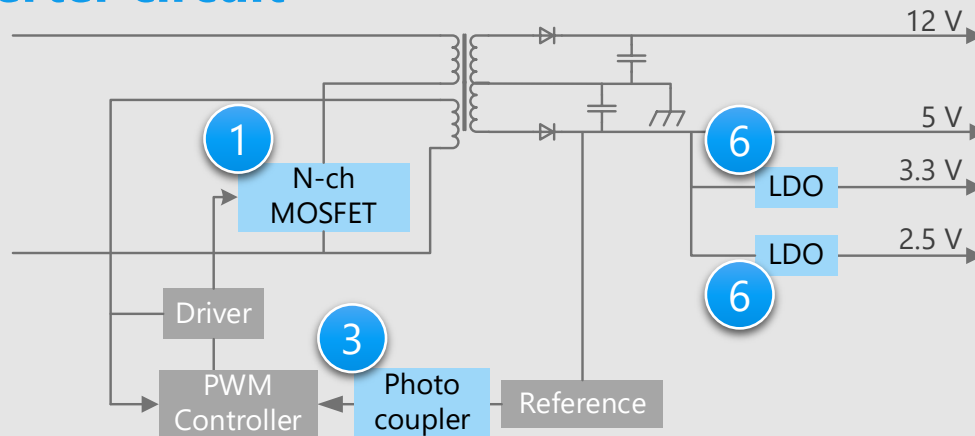
AC-DC converter circuit

Outdoor unit



AC-DC converter circuit

Indoor unit



Criteria for device selection

- High voltage MOSFETs are suitable for primary switching of AC-DC converters.
- The transistor output photocoupler is for signal isolation.

Proposals from Toshiba

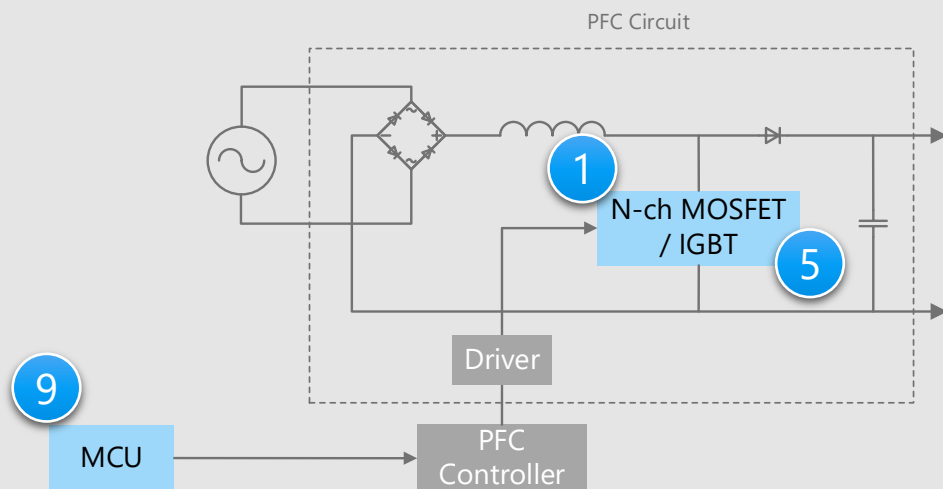
- **Suitable for high efficiency power supply switching** (1)
DTMOSVI Series MOSFET
- **High current transfer ratio and high temperature operation have been achieved** (3)
Transistor output photocoupler
- **Supply the power with low noise** (6)
Small surface mount LDO regulator

* [Click on the numbers in the circuit diagram to jump to the detailed descriptions page](#)

Air Conditioner Details of PFC unit

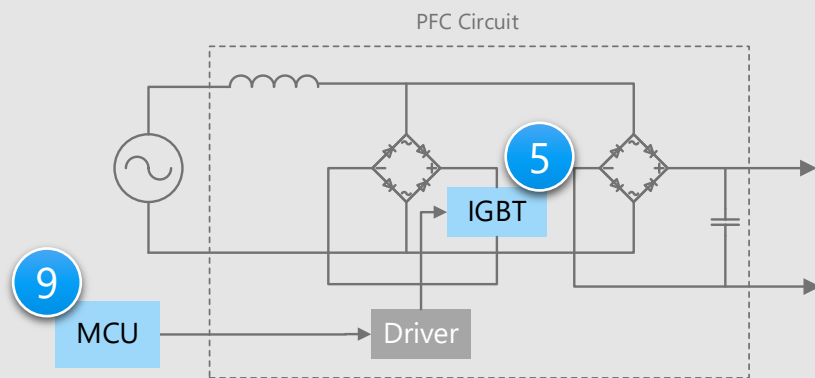
PFC circuit

Active type



PFC circuit

Partial switching type



Criteria for device selection

- MOSFETs with high speed switching and low on-resistance are suitable for active type PFC circuit.
- IGBTs with low collector-emitter saturation voltage are suitable for partial switching type PFC circuit.

Proposals from Toshiba

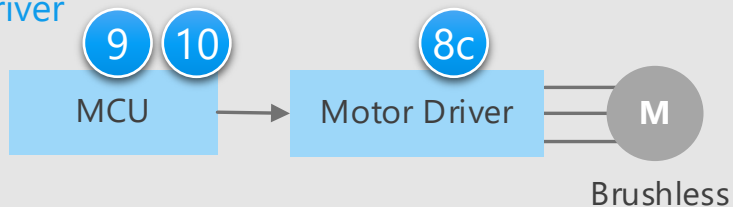
- **Suitable for high efficiency power supply switching**
DTMOSVI Series MOSFET 1
- **IGBT which is suitable for high voltage and high current system**
Discrete IGBT 5
- **Suitable for PFC and motor control**
MCU M4K Group / M470 Group / M370 Group 9

* [Click on the numbers in the circuit diagram to jump to the detailed descriptions page](#)

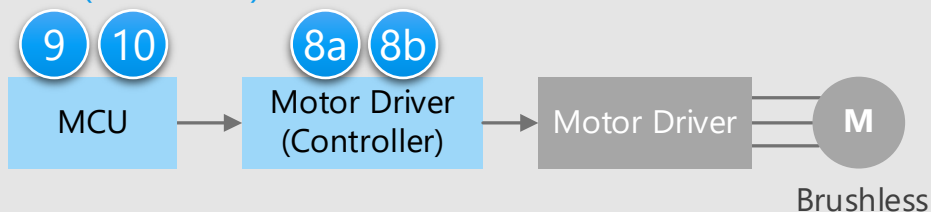
Air Conditioner Details of fan (indoor/outdoor) and compressor unit

Fan section (indoor/outdoor units)

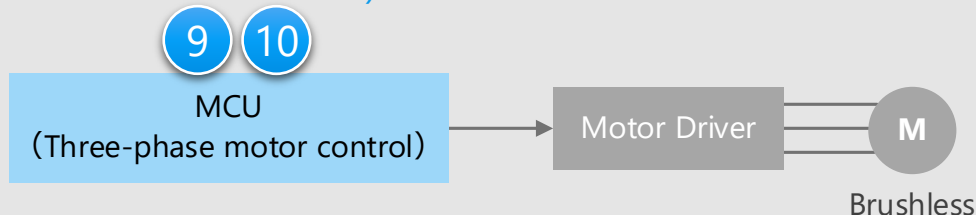
MCU + motor driver



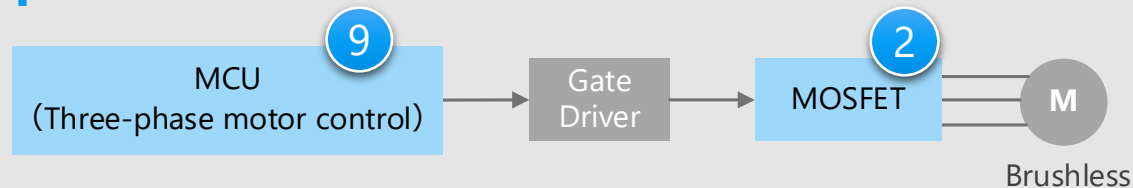
MCU + motor driver (controller) + motor driver



MCU (Three-phase motor controller) + motor driver



Compressor section



Criteria for device selection

- MOSFET with short reverse recovery time is suitable for motor drive in compressors.
- By using brushless motor drivers, three-phase brushless DC motors can be controlled easily.

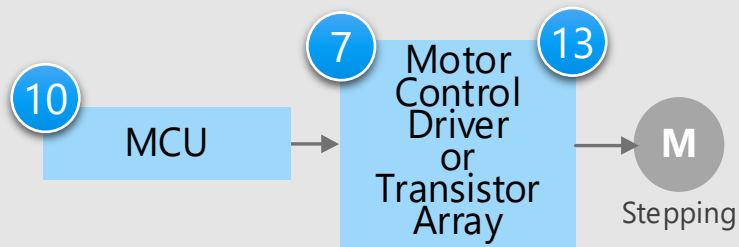
Proposals from Toshiba

- **Suitable for inverter** DTMOSIV(HSD) Series MOSFET 2
- **Easy motor drive** Three-phase brushless DC motor driver 8a 8b 8c
- **Suitable for PFC and motor control** MCU M4K Group / M470 Group / M370 Group 9
- **Easy software development using general purpose CPU cores** MCU M3H Group 10

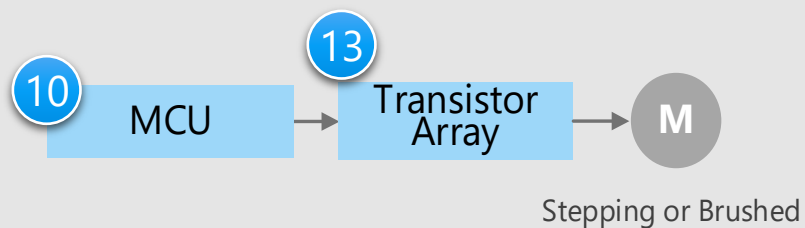
* [Click on the numbers in the circuit diagram to jump to the detailed descriptions page](#)

Air Conditioner Details of cleaning, louver and valve control unit

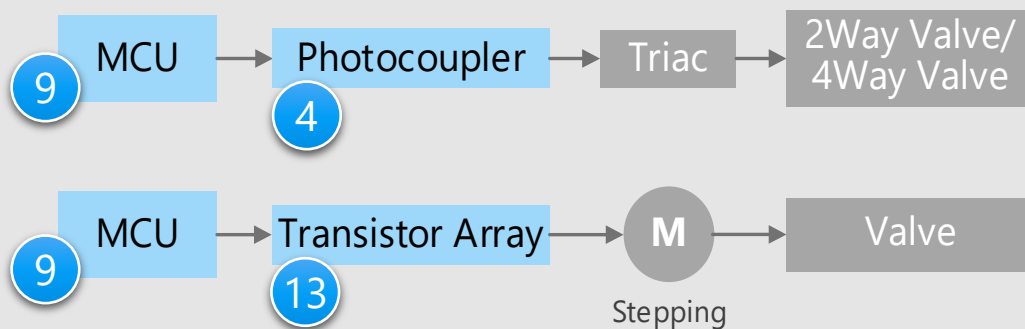
Cleaning section



Louver section



Valve control section



Criteria for device selection

- Stepping motor driver enables efficient motor control by optimizing real-time current to the motor.
- Brushed DC motor driver allows motor driving with low power consumption.

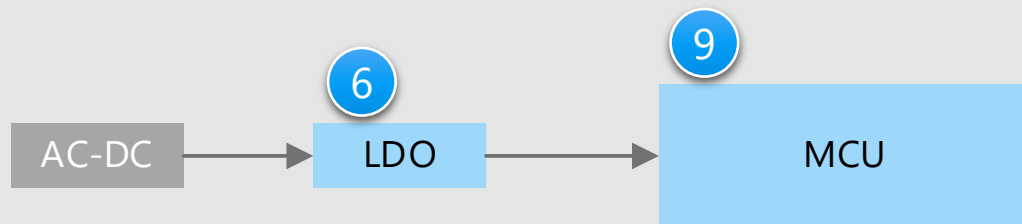
Proposals from Toshiba

- **Easy motor drive** Stepping motor & Brushed DC motor driver 7
- **Triac driver for high dv/dt** Triac output photocoupler 4
- **Suitable for PFC and motor control** MCU M4K Group / M470 Group / M370 Group 9
- **Easy software development using general purpose CPU cores** MCU M3H Group 10
- **High efficiency and high current driver with built-in low loss DMOS FET** Transistor array 13

* [Click on the numbers in the circuit diagram to jump to the detailed descriptions page](#)

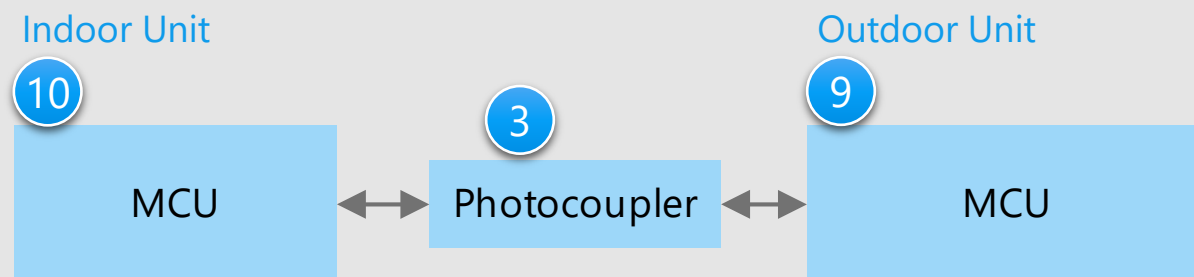
Microcontroller section

Power control block for outdoor unit



Isolation circuit

Between outdoor and indoor units



Criteria for device selection

- Isolation devices such as transistor output photocouplers are effective when voltage difference exists between outdoor and indoor GNDs.
- MCUs are suitable for system monitoring and control.

Proposals from Toshiba

- **High current transfer ratio and high temperature operation have been achieved**
Transistor output photocoupler
- **Supply the power with low noise**
Small surface mount LDO regulator
- **Suitable for PFC and motor control**
MCU M4K Group / M470 Group / M370 Group
- **Easy software development using general purpose CPU cores**
MCU M3H Group

3

6

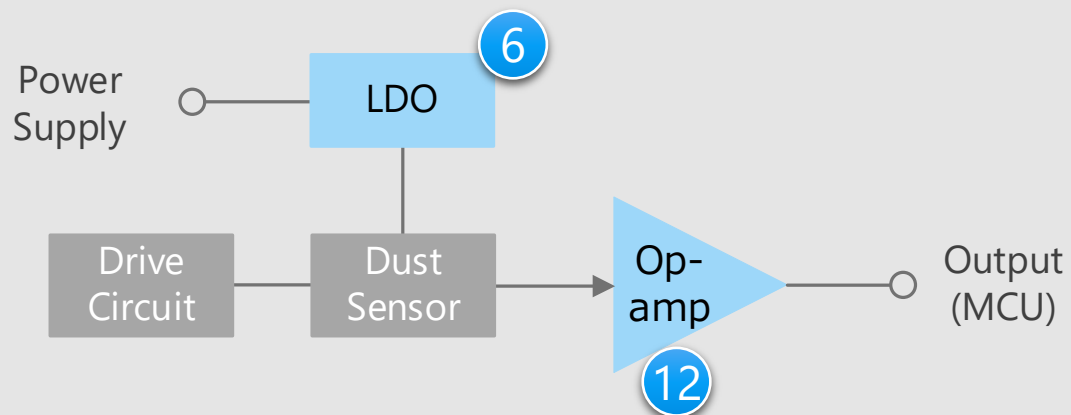
9

10

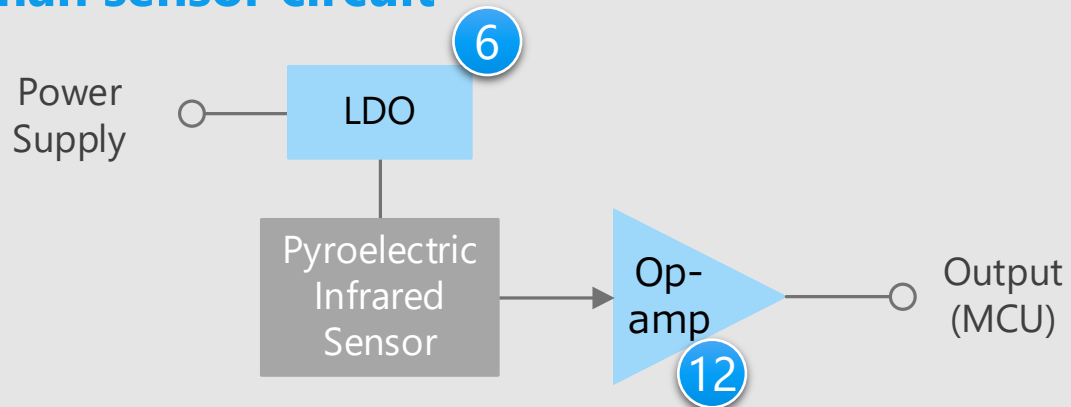
* [Click on the numbers in the circuit diagram to jump to the detailed descriptions page](#)

Air Conditioner Details of sensor input unit (1)

Dust sensor circuit



Human sensor circuit



Criteria for device selection

- PSRR (Power Supply Rejection Ratio) of LDO regulator is an important parameter for sensor modules.
- The operational amplifier should be low current consumption or low noise device.
- Small package products contribute to the reduction of circuit board area.

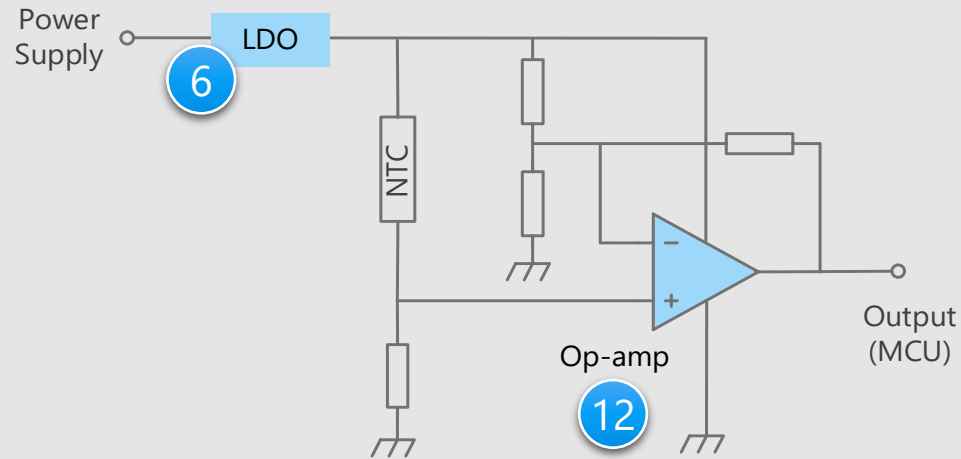
Proposals from Toshiba

- **Supply the power with low noise**
Small surface mount LDO regulator 6
- **Amplification of detected very small signal with low noise**
Low current consumption op-amp / Low noise op-amp 12

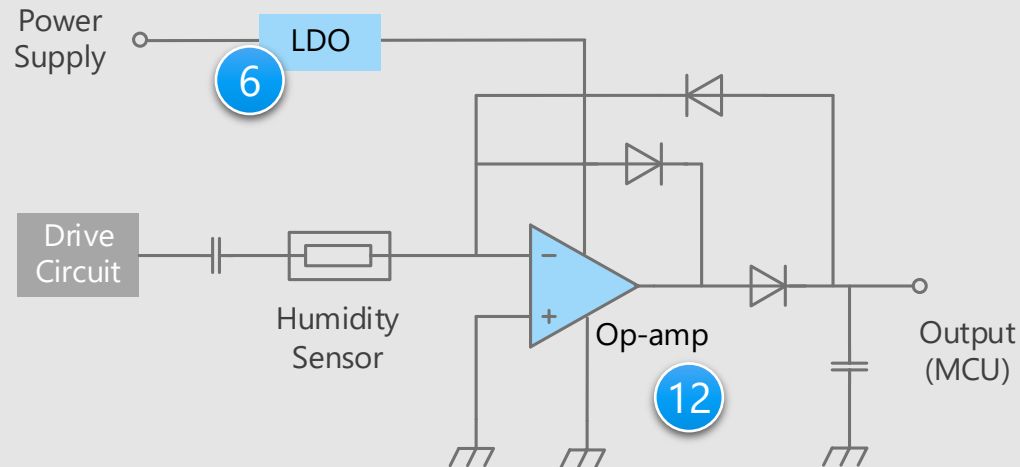
* [Click on the numbers in the circuit diagram to jump to the detailed descriptions page](#)

Air Conditioner Details of sensor input unit (2)

Temperature sensor circuit



Humidity sensor circuit



Criteria for device selection

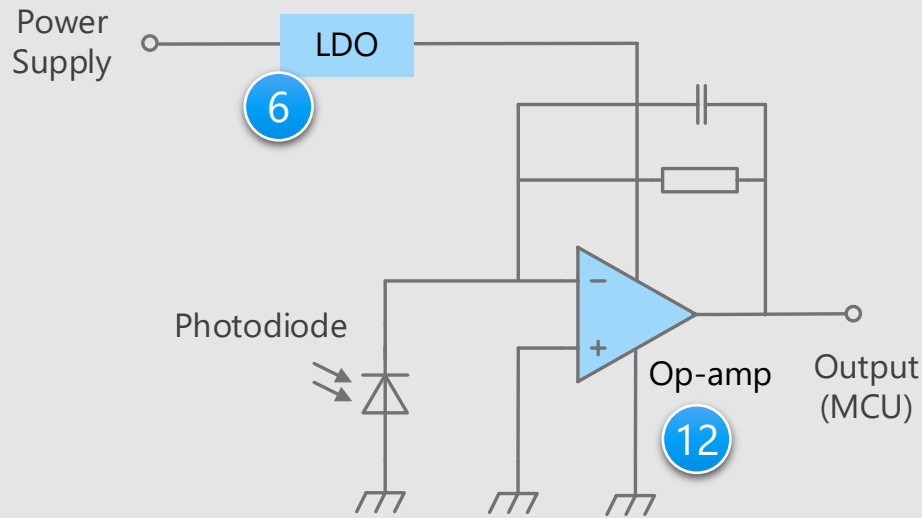
- PSRR (Power Supply Rejection Ratio) of LDO regulator is an important parameter for sensor modules.
- The operational amplifier should be low current consumption or low noise device.
- Small package products contribute to the reduction of circuit board area.

Proposals from Toshiba

- **Supply the power with low noise**
Small surface mount LDO regulator 6
- **Amplification of detected very small signal with low noise**
Low current consumption op-amp / Low noise op-amp 12

* Click on the numbers in the circuit diagram to jump to the detailed descriptions page

Ambient light sensor circuit



Criteria for device selection

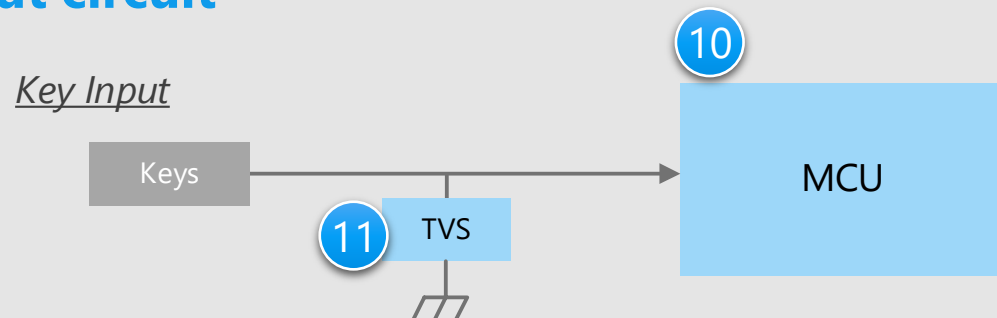
- PSRR (Power Supply Rejection Ratio) of LDO regulator is an important parameter for sensor modules.
- The operational amplifier should be low current consumption or low noise device.
- Small package products contribute to the reduction of circuit board area.

Proposals from Toshiba

- **Supply the power with low noise**
Small surface mount LDO regulator 6
- **Amplification of detected very small signal with low noise**
Low current consumption op-amp / Low noise op-amp 12

* [Click on the numbers in the circuit diagram to jump to the detailed descriptions page](#)

Key input circuit



Criteria for device selection

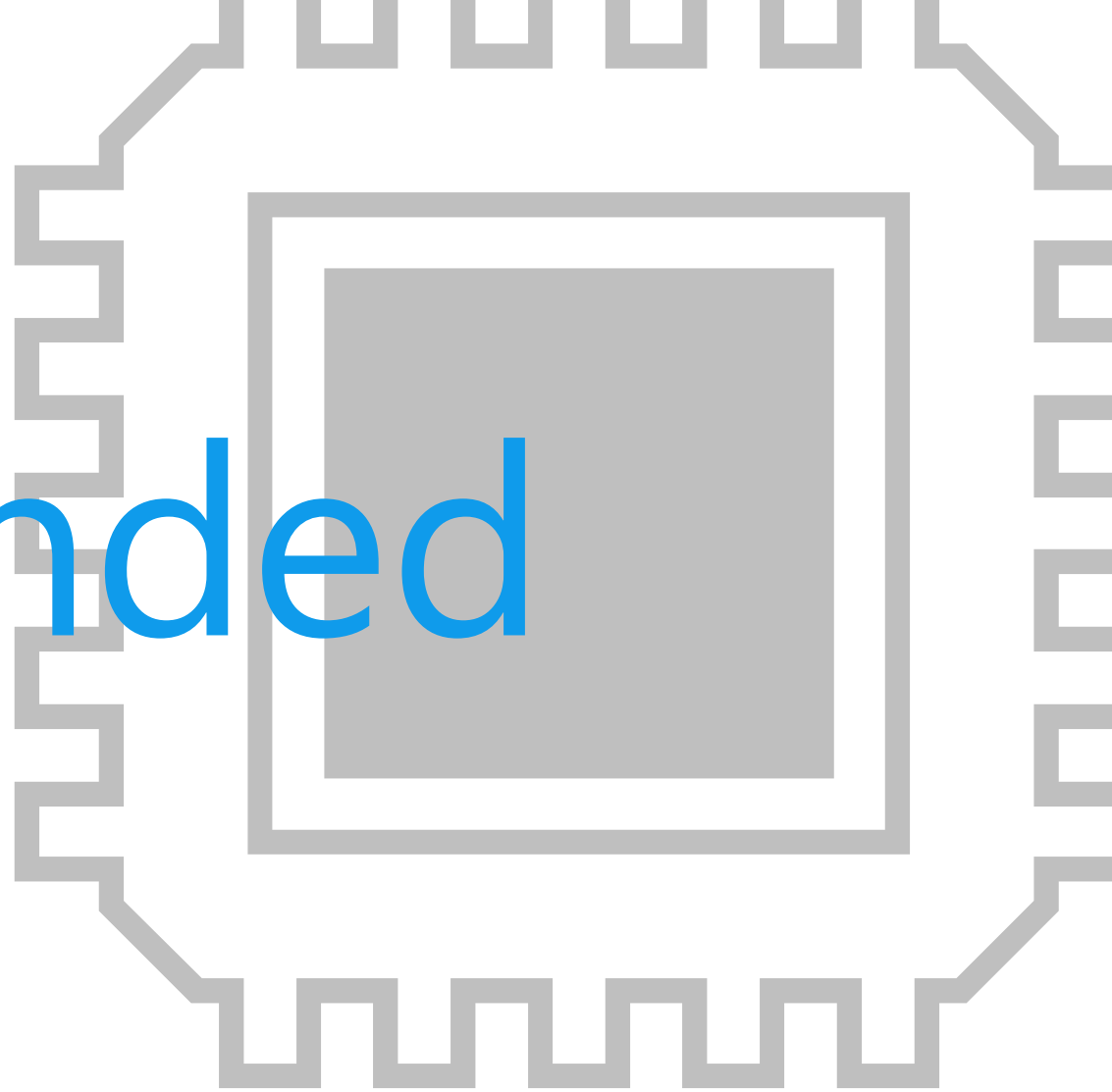
- TVS diodes are suitable for protection from ESD pulses coming in key input unit.
- Small package products contribute to the reduction of circuit board area.

Proposals from Toshiba

- **Easy software development using general purpose CPU cores**
MCU M3H Group 10
- **Absorb static electricity (ESD) to prevent malfunction of the circuit**
TVS diode 11

* [Click on the numbers in the circuit diagram to jump to the detailed descriptions page](#)

Recommended Devices



Device solutions to address customer needs

As described above, in the design of air conditioner, “**Quietness/efficiency of motors**”, “**Low power consumption of the set**” and “**Miniaturization of circuit boards**” are important factors. Toshiba’s proposals are based on these three solution perspectives.

Quietness/efficiency of motors



Low power consumption
of the set



Miniaturization of
circuit boards



Device solutions to address customer needs

	Brushless DC motor drive	High efficiency - low loss	Small size packages
1 DTMOSVI Series MOSFET	●	●	●
2 DTMOSIV (HSD) Series MOSFET	●	●	●
3 Transistor output photocoupler		●	●
4 Triac output photocoupler		●	●
5 Discrete IGBT	●	●	●
6 Small surface mount LDO regulator		●	●
7 Stepping motor & Brushed DC motor driver	●	●	●
8 Three-phase brushless DC motor driver	●	●	●
9 MCU M4K Group / M470 Group / M370 Group	●	●	●
10 MCU M3H Group	●	●	●

Device solutions to address customer needs

Brushless
DC motor
drive

High
efficiency
·
low loss

Small size
packages

11	TVS diode		●
12	Low current consumption op-amp / Low noise op-amp	●	●
13	Transistor array	●	●

Value provided

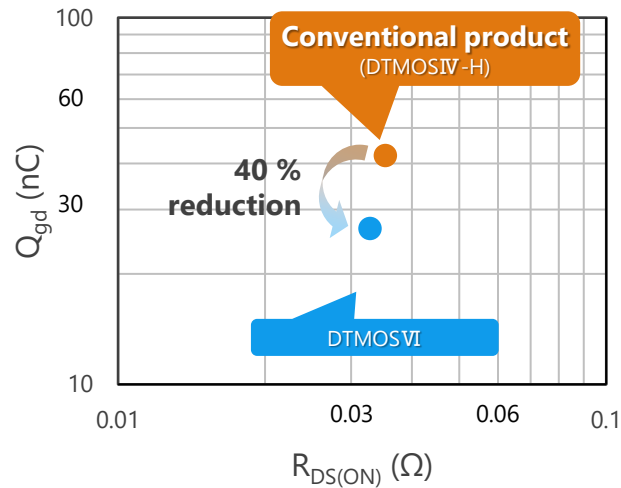
Improved performance index $R_{DS(on)} \times Q_{gd}$, which shows switching characteristic, contributes to improvement of power supply efficiency.

1 $R_{DS(ON)} \times Q_{gd}$ improvement

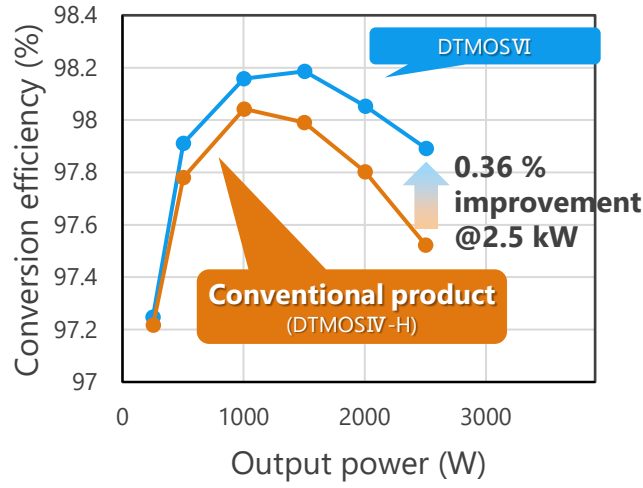
The $R_{DS(ON)} \times Q_{gd}$ figure of merit has been reduced by 40 % with gate design and process optimization.

(Comparison with DTMOSIV-H products: Toshiba internal comparison)

This characteristic improvement reduces switching loss and contributes to improving power supply efficiency of equipment.



[Note] Toshiba internal comparison







[Note] Toshiba internal comparison

2 RonA improvement

The RonA figure of merit has been reduced by 18 %. (Comparison with DTMOSIV 650 V products: Toshiba internal comparison).

Achieves low on-resistance while ensuring high voltage compared to Toshiba's existing products, contributing to improved power supply efficiency of equipment.

Lineup

Part number	TK200U65Z5	TK065U65Z	TK200A65Z5	TK040N65Z	
Package	TOLL  		TO-220SIS 	TO-247 	
V _{DSS} [V]	650				
I _D [A]	15	38	15	57	
R _{DS(ON)} [Ω] @V _{GS} = 10 V	Typ.	0.154	0.051	0.154	0.033
	Max	0.200	0.065	0.200	0.040
Polarity	N-ch				

[Return to Block Diagram TOP](#)

Value provided

The figure of merit RonA has been reduced by 30 % (compared with Toshiba’s existing products), then contribute to improve efficiency of power supply.

1 RonA 30 % reduction

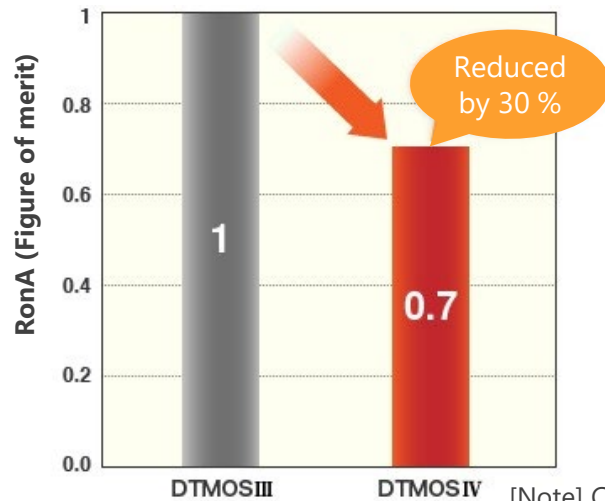
Adoption of single epitaxial process to reduce the figure of merit RonA by 30 %. (Compared with Toshiba DTMOSIII products)

2 Reduction of on-resistance increase at high temperature



The single epitaxial process reduces the on-resistance increase at high temperature.

3 Optimization of switching speed

Optimization of switching speed has been achieved by reduction of C_{OSS} and other factors.



[Note] Compared with Toshiba DTMOSIII products

Part number		TK20A60W5	
Package	TO-220SIS		
V _{DSS} [V]	600		
I _D [A]	20		
R _{DS(ON)} [Ω] @V _{GS} = 10 V	Typ.	0.15	
	Max	0.175	
Polarity	N-ch		

[Return to Block Diagram TOP](#)

Value provided

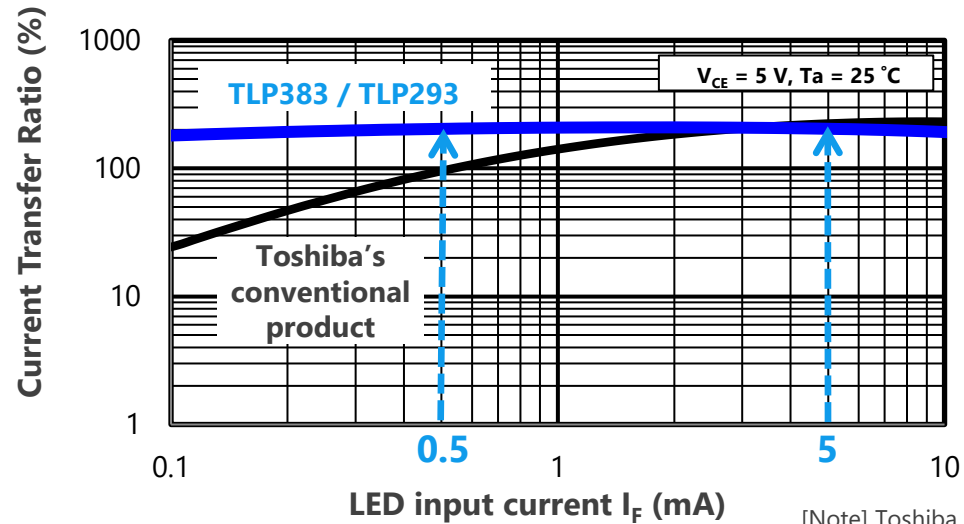
High CTR (Current Transfer Ratio) is realized even in low input current range ($I_F = 0.5 \text{ mA}$).

1 High current transfer ratio

The TLP383 and TLP293 is a high isolation photocoupler that optically couples a phototransistor and high output infrared LED. Compared to Toshiba's existing products (TLP385), higher CTR (Current Transfer Ratio) in low input current range (@ $I_F = 0.5 \text{ mA}$) is realized.

2 High temperature operation

The TLP383 and TLP293 are designed to operate even under severe ambient temperature conditions.



[Note] Toshiba internal comparison

Lineup

Part number	TLP383	TLP293	TLP385
Package	4pin SO6L 	SO4 	4pin SO6L 
BV_S [Vrms]	5000	3750	5000
T_{opr} [$^\circ\text{C}$]	-55 to 125	-55 to 125	-55 to 110

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4 Triac output photocoupler

TLP3083 / TLP3073

Brushless
DC motor
drive

High
efficiency
·
low loss

Small size
packages

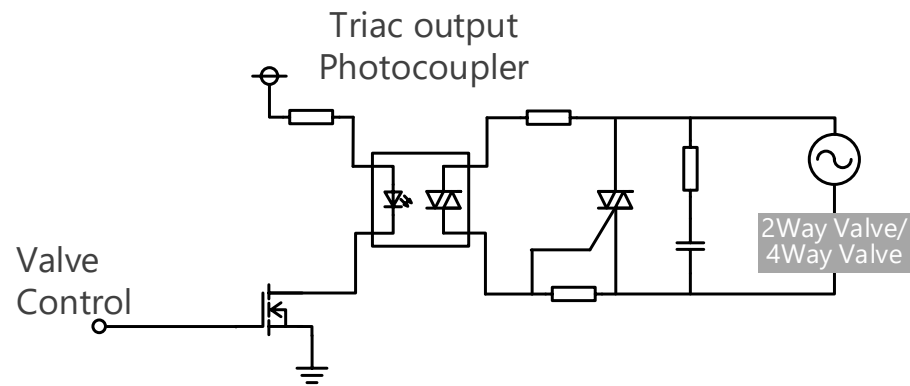
Value provided

Using a triac with high dv/dt pre-driver for solenoid valve control suppresses false turn-on.

1 Low input and zero crossing input control

This device optically couples a photo triac and a high power infrared LED, providing high isolation equivalent to an electromagnetic relay. Capable of low input operation, the photo coupler can be directly controlled by a microcontroller.


■ Example of AC switch using triac output photocoupler



2 High dv/dt

The TLP3083 is a triac having a high dv/dt of 2000 V/μs (typ.). With a high OFF-state voltage of 800 V, it can work with various AC power supplies.

Lineup

Part number	TLP3083	TLP3073
Package	5pin DIP6 	
Output type	Zero crossing functionary (ZC)	Non zero crossing functionary (NZC)
BV _S [Vrms]	5000	
T _{opr} [°C]	-40 to 100	

[◆Return to Block Diagram TOP](#)

Value provided

Switching devices for high voltage (600 V or more) and high current (30 A or more) application. Lineup of low $V_{CE(sat)}$ products are effective in reducing conduction loss.

1 High speed, low saturation voltage

By adopting a thin wafer punch-through structure, high speed turn-off characteristics and low $V_{CE(sat)}$ characteristics are realized.

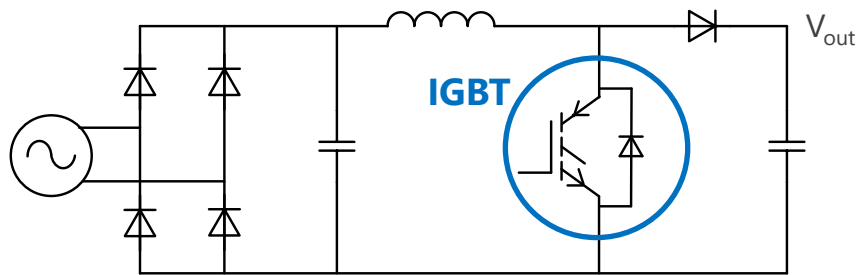
2 High breakdown tolerance

Toshiba has a lineup of products with high breakdown tolerance (short circuit withstand time t_{sc} and reverse bias safe operating area RBSOA).


3 Enhancement type

Since collector current does not flow when gate voltage is not applied for enhancement devices, handling is easy.

Active type PFC circuit example using discrete IGBT (GT50JR22)


 $f_{sw} = 20 \text{ to } 35 \text{ kHz}$

Lineup

Part number	GT50JR22	GT50J123	GT30J65MRB
Package	TO-3P(N) 		
Built-in FWD	✓ (RC structure)	-	✓ (RC structure)
V_{CES} [V]	600	600	650
I_C [A]	50	59	60
$V_{CE(sat)}$ [V] @ $I_C = 50 \text{ A}$, $V_{GE} = 15 \text{ V}$, $T_a = 25^\circ\text{C}$	Typ.	1.55	1.40 @ $I_C = 30 \text{ A}$
	Max	2.20	1.80 @ $I_C = 30 \text{ A}$
Breakdown tolerance	t_{sc} [μs]	-	5
	RBSOA	-	120 A, 600 V (full square)

[◆Return to Block Diagram TOP](#)

6 Small surface mount LDO regulator

TCR15AG / TCR8BM / TCR5FM / TCR5RG / TCR3RM / TCR3U / TCR3LM / TCR3D / TCR3EM / TCR1HF Series

Brushless DC motor drive

High efficiency
low loss

Small size packages

Value provided

Wide lineup from general purpose type to WCSP (Wafer Level Chip Size Package) type are provided. Contribute to realize a stable power supply.

1 Low dropout voltage

Low dropout voltage characteristic has been realized by the originally developed process.

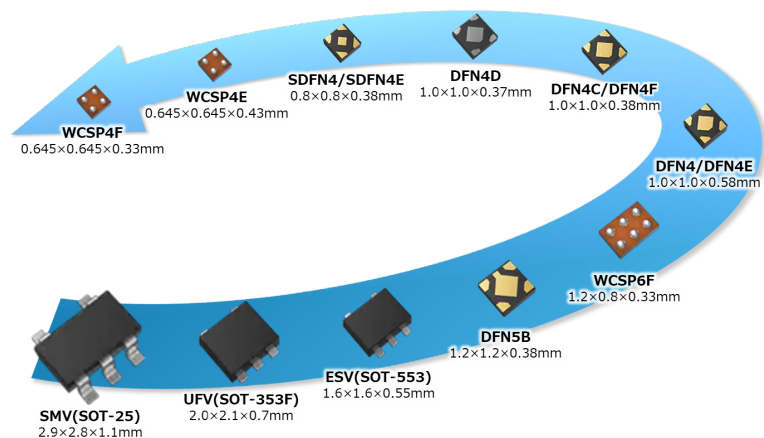
2 High PSRR Low output noise voltage

Many product series that realize both high PSRR (Power Supply Rejection Ratio) and low output noise voltage characteristics are provided. They are suitable for stable power supply for analog circuit.

3 Low current consumption

$I_{B(ON)}$ of 0.34 μA (typ.) @ $I_{OUT} = 0 \text{ mA}$, $V_{OUT} \leq 1.5 \text{ V}$ is realized by utilizing CMOS process and unique circuit technology. (TCR3U Series)

Rich package lineup



Lineup

Part number	TCR15AG Series	TCR8BM Series	TCR5FM Series	TCR5RG Series	TCR3RM Series	TCR3U Series	TCR3LM Series	TCR3D Series	TCR3EM Series	TCR1HF Series
Features	Low dropout voltage High PSRR		High PSRR Low noise Low current consumption			Low current consumption		Standard type		36 V Input voltage
I_{OUT} (Max) [A]	1.5	0.8	0.5			0.3				0.15
PSRR (Typ.) [dB] @f = 1 kHz	95	98	91	100	100	70	-	72	68	70
I_B (Typ.) [μA]	25	20	10	7	7	0.34	1	86	35	170

[Return to Block Diagram TOP](#)

Value provided

Support low voltage motor drive (2.5 V (Min)) and contributes to the power saving of set.

1 Low voltage operation

Motor power supply voltage is 2.5 V (Min) for low voltage applications.

2 Low current consumption

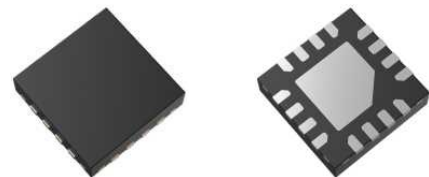
Standby current (IC total) is 2 μ A or less (IC total) for power saving of devices.

3 Error detection functions

Over current detection (ISD), thermal shutdown (TSD) and under voltage lockout (UVLO) are available.



P-TSSOP16-0505-0.65-001
(5.0 x 6.4 x 1.2 mm)



Top view

Bottom view

P-VQFN16-0303-0.50-001
(3.0 x 3.0 x 0.9 mm)

Lineup

Part number	TC78H621FNG	TC78H660FNG	TC78H660FTG
V_M [V]	18	18	18
I_{OUT} [A]	1.1	2.0	2.0
$R_{on(U+L)}$ (Typ.) [Ω]	0.8	0.48	0.48
Control interface	PHASE input	IN/PHASE inputs	IN/PHASE inputs
Step	2phase/1-2phase excitation	2phase/1-2phase excitation	2phase/1-2phase excitation
Motor power supply voltage	2.5 V (Min)	2.5 V (Min) RS resistor less	2.5 V (Min) RS resistor less
Error detection function	ISD, TSD, UVLO	ISD, TSD, UVLO	ISD, TSD, UVLO
Package	P-TSSOP16-0505-0.65-001		P-VQFN16-0303-0.50-001

[◆Return to Block Diagram TOP](#)

Value provided

Toshiba's proprietary technology eliminates the need for phase adjustment and achieves high efficiency for a wide range of rotation speeds.

1 High efficiency in a wide range of rotation speeds

Toshiba's automatic lead angle control technology realizes a high efficiency drive regardless of motor speed, load torque or power supply voltage.

2 Motor control with low noise and low vibration

Sine wave drive system with smooth current waveforms contributes to lower motor noise and vibration compared to conventional square wave drive system ^[Note].

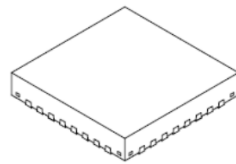
[Note] Comparison with Toshiba products

3 Small size package

VQFN32 package is adopted for TC78B042FTG, which requires small space. SSOP30 package is adopted for TC78B041FNG as conventional type.



SSOP30-P-300-0.65
(10.2 x 7.6 x 1.6 mm)



P-VQFN32-0505-0.50-005
(5.0 x 5.0 x 1.0 mm)

Lineup

Part number	TC78B041FNG	TC78B042FTG
Power supply voltage	6 to 16.5 V (operating range)	
Drive type	Sine wave drive	
Features	Auto lead angle control for optimizing voltage and current phases	
	Hall element or hall IC input	
	Forward/reverse rotation switch	
	Motor lock detection	
	Selectable pulse number of rotation pulse signal output	
	Built-in 5 V regulator (VREF pin)	Built-in 5 V regulator (VREF/VREF2 pin)
Error detection positive input	Error detection positive/negative input	
Package	SSOP30-P-300-0.65	P-VQFN32-0505-0.50-005

[◆Return to Block Diagram TOP](#)

Value provided

High voltage and high current brushless DC motor driving can be implemented by using with external power devices.

1 High efficient motor control by automatic phase control

Automatic phase controller by current feedback is integrated adding conventional fixed phase voltage input (32 steps).

2 Motor control with low noise and low vibration

Sine wave drive system with smooth current waveforms contributes to lower motor noise and vibration compared to conventional square wave drive system ^[Note].

[Note] Comparison with Toshiba products

3 Sufficient development support

Various supports such as third party evaluation board and PSpice® data for development and design are prepared.



SSOP30-P-300-0.65 package
(10.2 x 7.6 x 1.6 mm)

Lineup

Part number	TB6584FNG	TB6584AFNG	TB6634FNG
Supply voltage	6 to 16.5 V (operating range)		
Output current	0.002 A (for MOSFET driver)		
Drive mode	Sine wave drive		
Features	Lead angle control: Auto phase control (current feedback) Sensor input: Hall device/Hall IC compatible Internal regulator: 5 V, 30 mA (Max) Error detection: overcurrent protection, abnormal position signal protection, undervoltage lockout, motor restrained detection (TB6634FNG)		

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Value provided

A motor control IC and IGBTs are integrated into one package, contributing to the miniaturization of circuit boards.

1 A motor control IC and IGBTs

A motor control IC with sine wave PWM drive function and IGBTs with 600 V and 2 A characteristics are integrated into one package.

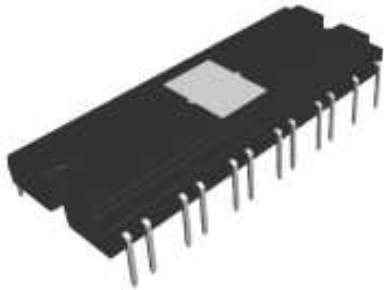
2 Motor control with low noise and low vibration

Sine wave drive system with smooth current waveforms contributes to lower motor noise and vibration compared to conventional square wave drive system ^[Note].

[Note] Comparison with Toshiba products

3 High heat dissipation

HDIP30 package is adopted for TB67B000AHG, which has high heat dissipation. HSSOP34 package is adopted for TB67B000AFG, which is smaller than HDIP30.



P-HDIP30-1233-1.78-001
(32.8 x 13.5 x 3.525 mm)



P-HSSOP34-0918-0.80-001
(17.5 x 11.93 x 2.2 mm)

Lineup

Part number	TB67B000AHG	TB67B000AFG
Operating voltage range	Power supply for control: 13.5 to 16.5 V	
	Power supply for motor drive: 50 to 450 V	
Output current	2 A	
Drive type	Sine wave PWM drive / Wide angle commutation	
Lead angle control	0 to 58 degrees 32 steps / 0 to 28 degrees 16 steps	
Speed command input voltage	Motor operation: 2.1 to 5.4 V	
Features	IGBT three-phase bridge, oscillator circuit, built-in bootstrap diode, overcurrent protection, thermal shutdown, undervoltage lockout, motor lock detection	
Package	P-HDIP30-1233-1.78-001	P-HSSOP34-0918-0.80-001

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Value provided

System cost reduction, higher efficiency and less development work.

1 Equipped with motor control co-processor

Toshiba's original co-processor vector engine (VE) for motor control reduces CPU load and allows control of multiple motors and peripherals. [Note 1]

[Note 1] VE is integrated into some products

2 Equipped with motor control circuit

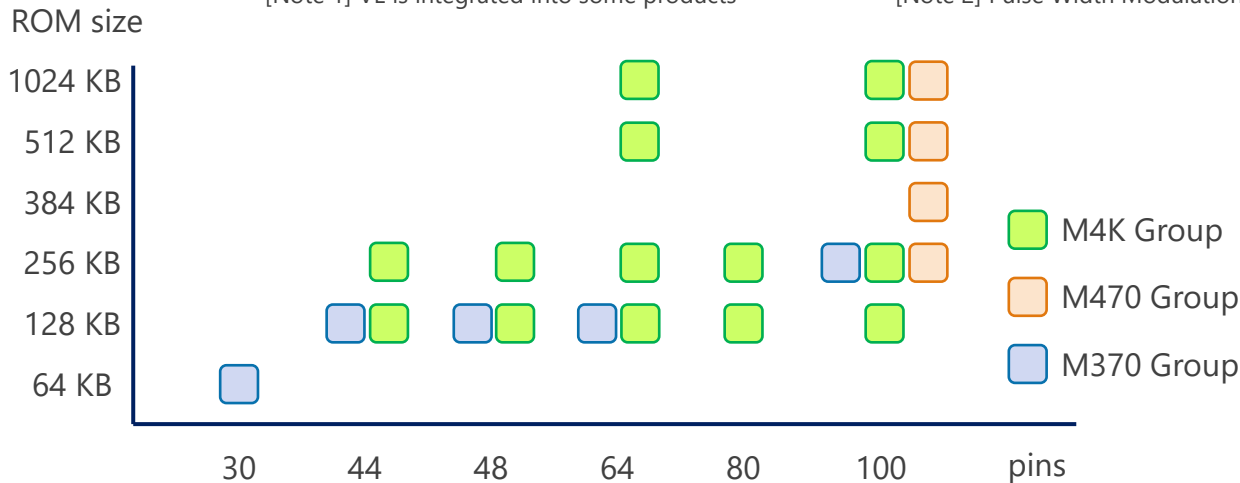
A variety of three-phase PWM [Note 2] waveforms and AD converters enable highly efficient, low noise control. The Advanced Encoder (A-ENC) reduces the load of CPU process in detecting the position performed for each PWM.

[Note 2] Pulse Width Modulation

3 Provide development support tools

Third party evaluation boards and sample programs that can be used to shorten the development time are provided. Toshiba has also offered new, simple, versatile motor control software development kits (MCU Motor Studio). [Note 3]

[Note 3] MCU Motor Studio supports some products and will expand in TXZ+™ family.



Lineup

Series	Group	Function
TXZ+™ 4A Series	M4K Group	Arm® Cortex®-M4, Max. 160 MHz operation 4.5 to 5.5 V, 3motor control (Max), Data Flash
TX04 Series	M470 Group	Arm® Cortex®-M4, Max. 160 MHz operation 4.5 to 5.5 V, 2motor control (Max)
TX03 Series	M370 Group	Arm® Cortex®-M3, 80 MHz operation 4.5 to 5.5 V, 2motor control (Max)

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Value provided

MCU is equipped with many peripheral functions. MCU contributes to higher functionality as a system control MCU.

1 Built-in Arm® Cortex®-M3 CPU core

MCU is equipped with Arm® Cortex®-M3 core. Maximum operation frequency is 120 MHz.

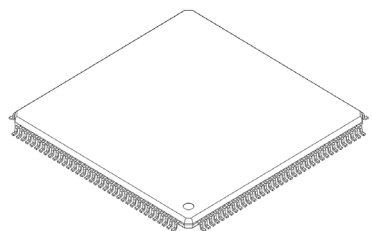
2 Various lineup of built-in memories and packages

M3H group integrates both 512 KB (Max) code and 32 KB data flash memories which support 100,000 write cycle endurance (Max), and has a wide lineup of package from 64 to 144 pins.

3 Equipped with many peripheral functions

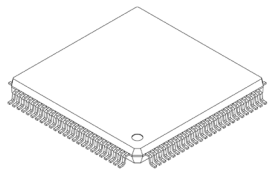
M3H Group have many peripheral functions such as UART, SPI, I²C, 12bit AD converter, 8bit DA converter, three-phase PWM [Note1] output, ENC and digital LCD driver [Note2], etc.

TMPM3HQF10BFG
TMPM3HQFDAFG



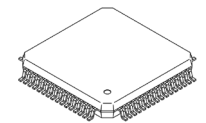
P-LQFP144-2020-0.50-002
(22.0 x 22.0 x 1.7 mm)

TMPM3HNF10BFG
TMPM3HNFDAFG



P-LQFP100-1414-0.50-002
(16.0 x 16.0 x 1.7 mm)

TMPM3HLF10BUG
TMPM3HLFDAUG



P-LQFP64-1010-0.50-003
(12.0 x 12.0 x 1.7 mm)

[Note 1] Pulse Width Modulation

[Note2] 64 pin products aren't equipped with digital LCD driver.

Lineup

Part number	M3H (2)	TMPM3HQF10BFG	TMPM3HNF10BFG	TMPM3HLF10BUG
	M3H (1)	TMPM3HQFD/Z/Y/AFG	TMPM3HNFD/Z/Y/AFG	TMPM3HLFD/Z/Y/AUG
Max. operation frequency	120 MHz			
ROM (Flash)	M3H (2)	1024 KB		
	M3H (1)	512 / 384 / 256 KB		
RAM	M3H (2)	130 KB (with parity)		
	M3H (1)	66 KB (with parity)		
Timer	32bit x 8ch (16bit x 16ch)			
AD converter	21ch (12bit)		17ch (12bit)	12ch (12bit)
Serial communication	UART: 8ch, I ² C: 4ch, TSPI: 5ch		UART: 8ch, I ² C: 3ch, TSPI: 4ch	UART: 7ch, I ² C: 2ch, TSPI: 1ch
Package	P-LQFP144-2020-0.50-002		P-LQFP100-1414-0.50-002	P-LQFP64-1010-0.50-003

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Value provided

Absorbs static electricity (ESD) from external terminals, prevents circuit malfunction and protects devices.

1 High ESD pulse absorption performance

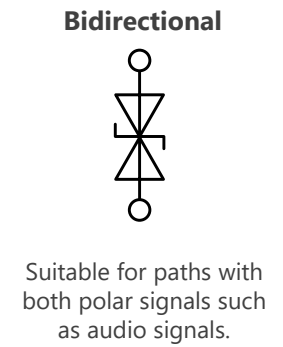
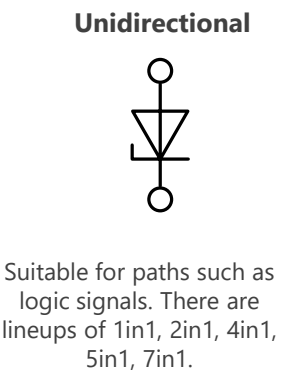
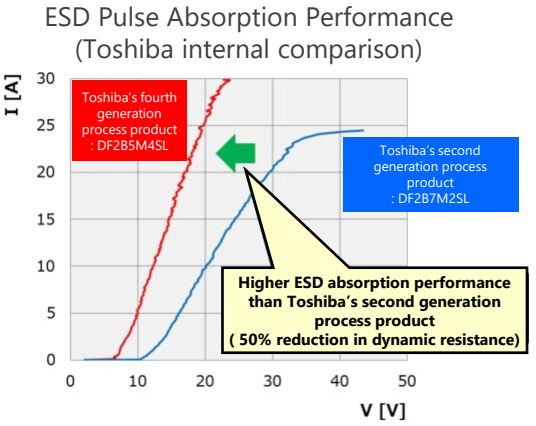
Improved ESD absorption compared to Toshiba's conventional products. (50 % reduction in operating resistance) For some products, both low operating resistance and low capacitance are realized and ensures high signal protection performance and signal quality.



2 Suppress ESD energy by low clamp voltage

Protect the connected circuits and devices using Toshiba own technology.

3 Suitable for high density mounting

A variety of small size packages are available.



Lineup			
Part number	DF2B7BSL	DF2B5M4SL	DF2B6M4SL
Package	SL2	 Top view	 Bottom view
V_{ESD} [kV]	±30	±20	±20
V_{RWM} (Max) [V]	5.5	3.6	5.5
C_t (Typ.) [pF]	12	0.2	0.2
R_{DYN} (Typ.) [Ω]	0.2	0.5	0.5

(NOTE) This product is an ESD protection diode and cannot be used for purposes other than ESD protection.

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Value provided

The lineup includes a low current consumption type that contributes to reducing power consumption and a low noise type that brings out performance of the sensor.

1 Low voltage operation

We have a lineup of low power supply voltage-driven operational amplifiers using CMOS process for low power supply voltage-driven wearable equipment.

2 Low current consumption (TC75S102F) $I_{DD} = 0.27$ [μA] (Typ.)

CMOS processes have been used to achieve lower current consumption. This contributes to lower power consumption and longer life of wearable equipment.

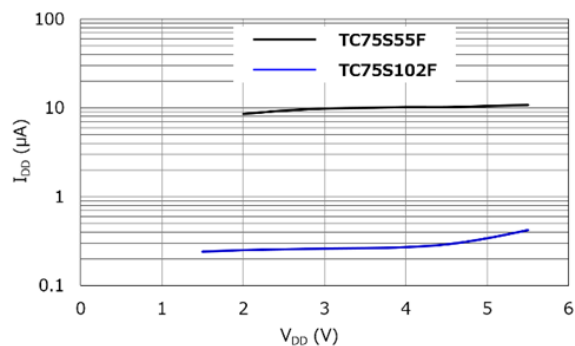
3 Low noise (TC75S67TU) $V_{NI} = 6.0$ [$\text{nV}/\sqrt{\text{Hz}}$] (Typ.) @ $f = 1$ kHz

This CMOS operational amplifier can amplify minute signals detected by various sensors [Note] with low noises. By optimizing the process, the equivalent input noise voltage has been reduced.

[Note] Sensor types: vibration, shock, acceleration, pressure, infrared, temperature, etc.

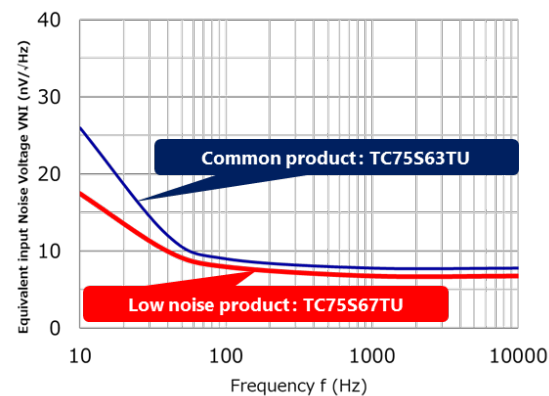
TC75S102F

Current Consumption Characteristic
(Toshiba internal comparison)





TC75S67TU

Noise Characteristic
(Toshiba internal comparison)



Lineup

Part number	TC75S102F	TC75S67TU
Package	SMV 	UFV 
$V_{DD} - V_{SS}$ [V]	1.5 to 5.5	2.2 to 5.5
V_{IO} (Max) [mV]	1.3	3
CMV_{IN} (Max) [V]	V_{DD}	1.4 (@ $V_{DD} = 2.5$ V)
I_{DD} (Typ. / Max) [μA]	0.27 / 0.46 (@ $V_{DD} = 1.5$ V)	430 / 700 (@ $V_{DD} = 2.5$ V)
V_{NI} (Typ.) [$\text{nV}/\sqrt{\text{Hz}}$] @ $f = 1$ kHz	-	6.0

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Value provided

DMOS FET is used for the output of drive circuit and realizes low loss. And CMOS input can control directly from controller's I/O, etc.

1 Rich product lineup

In addition to the listed products, we have lineup of various packaged products (such as DIP, SOL, SOP, SSOP, etc.) and source output type products.

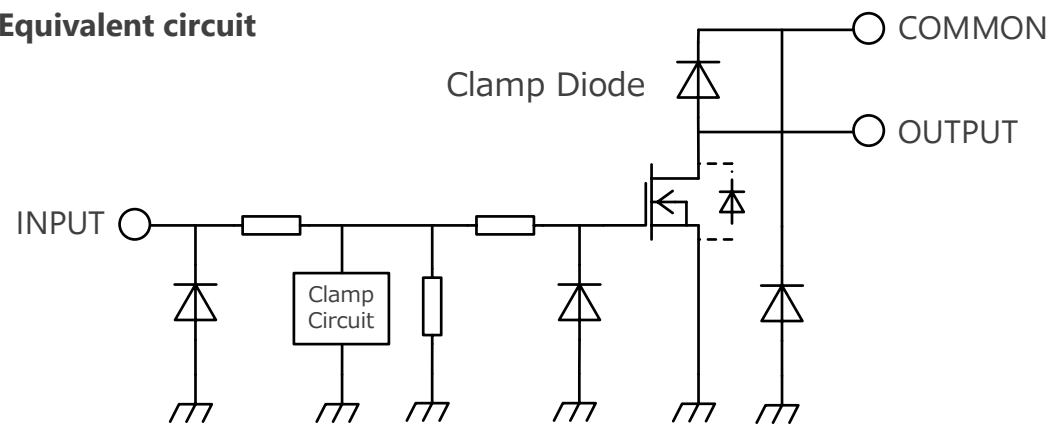
2 Built-in output clamp diode

Built-in output clamp diode regenerates the back electromotive force generated by switching of an inductive.

3 Higher current drive is possible

The load can be driven with higher current by connecting multiple outputs in parallel.

Equivalent circuit



[Note] Equivalent circuit may be simplified for explanatory purpose.

Lineup

Part number	TBD62003AFWG	TBD62083AFG	TBD62064AFAG
Package	P-SOP16-0410-1.27-002	SOP18-P-375-1.27	P-SSOP24-0613-1.00-001
Output type	Sink	Sink	Sink
Number of channels	7ch	8ch	4ch
Input level	H	H	H
I_{OUT} [mA/ch]	500	500	1500
V_{OUT} [V]	50	50	50

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